



Material Content Data Sheet



Sales Product Name		TLE4276G V50		Issued		10. August 2018		
MA#		MA001260928						
Package		PG-TO220-5-4		Weight*		1546.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.304	0.21	0.21	2136	2136
leadframe	inorganic material	phosphorus	7723-14-0	0.237	0.02		153	
	non noble metal	iron	7439-89-6	0.790	0.05		510	
	non noble metal	copper	7440-50-8	788.527	50.97	51.04	509744	510407
	non noble metal	aluminium	7429-90-5	0.274	0.02	0.02	177	177
wire	non noble metal	aluminium	7429-90-5	0.274	0.02	0.02	177	177
encapsulation	organic material	carbon black	1333-86-4	1.254	0.08		811	
	plastics	epoxy resin	-	57.684	3.73		37290	
	inorganic material	silicondioxide	60676-86-0	568.060	36.72	40.53	367222	405323
leadfinish	non noble metal	tin	7440-31-5	10.339	0.67	0.67	6684	6684
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.422	0.22	0.22	2212	2217
solder	non noble metal	tin	7440-31-5	0.099	0.01		64	
	noble metal	silver	7440-22-4	0.123	0.01		80	
	non noble metal	lead	7439-92-1	4.705	0.30	0.32	3041	3185
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.108	0.01		70	
	non noble metal	copper	7440-50-8	107.943	6.98	6.99	69780	69871
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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